

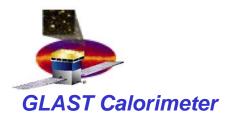
Monthly Cost / Schedule / Mission Dec 2003

## Monthly Cost/Schedule/Mission Review

### GLAST LAT Calorimeter December 15, 2003

William C. Raynor CAL Project Manager Naval Research Lab







Monthly Cost / Schedule / Mission Dec 2003

#### **Technical Status:**

- Last Month's Accomplishments
  - Summary of issues & concerns
  - Status/Closure of action items
- Open Design/Engineering model/manufacturing issues and closure plan for them
- □ Near-term Milestones & Status towards them for next 3 months





# **Significant Accomplishments**

November 2003

Monthly Cost / Schedule / Mission Dec 2003

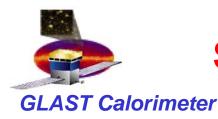
### **CDEs**

- Csl Crystals
  - To date Kalmar has delivered ~650 fully tested crystals to NRL. Flight deliveries to Swales have begun.
- PIN Photodiode Assembly (PDA)
  - ~1200 Dual PIN Photodiodes (corrected flight process) have been received from Hamamatsu
  - 50 copies of PDA tooling were manufactured and delivered to PDA assembly vendor.
  - First 150 flight PDAs have been manufactured, tested and delivered to Swales.

#### CDE Assembly Process

- 12 pre-Qual CDEs have successfully completed thermal cycling.
- 12 more Qual CDEs have been fab'ed.
- Production rate test build (60 CDE/week) was completed. Used 12 crystals and 48 Aluminum dummys. No production flow problems detected. Ready to build.
- Flight CDE build started December 8<sup>th</sup>.





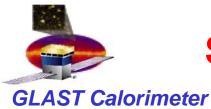
### Significant Accomplishments November 2003 (2)

Monthly Cost / Schedule / Mission Dec 2003

#### Mechanical Structure

- Revised, reviewed and released flight machined part drawings.
  - Final revisions of base plate drawing completed last week.
- Structural Model 2 (SM2 carbon composite structure) successfully completed strength test (LAT-SS-02052-01 == GLAST LLR-SP-078).
- Titanium insert cleaning and kitting is underway. Kits for FMA and FMB have been delivered to LLR.





### Significant Accomplishments November 2003 (3)

Monthly Cost / Schedule / Mission Dec 2003

#### □ AFEE Electronics

- Received Lot T31D ASICs (CAL and T&DF) from packaging at ASAT.
- Shipped Lot T36T ASICs (ACD, CAL and T&DF) to ASAT for packaging.
- Completed manufacture of ASIC burn-in boards.
- ASIC functional test GSE is essentially complete. They have been used to screen GCFE9A and GCRC5 chips to be placed on EM-version AFEE boards.
- Completed design and layout of ASIC functional test board that supports temperature forcing unit (tests at –30, +25 and +85 deg C).
- Four more EM AFEE cards were assembled for mini-EM to be delivered to SLAC.
- Flight AFEE layout is approaching completeness. 1<sup>st</sup> prototype was deemed unsatisfactory. Issue is placement of holes for PDA wires and areas for wire soldering and staking. New prototype next week.



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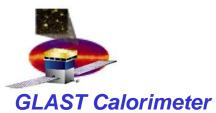
### Significant Accomplishments November 2003 (4)

Monthly Cost / Schedule / Mission Dec 2003

#### **EM CAL Module**

- Modified 2/4 AFEE for flight version of GCFE (9A). Works as well or better. Noise is somewhat higher however.
- Packed and shipped EM CAL and GSE to Darmstadt, Germany for heavy ion beam test at GSI.
- Successfully executed 10 nights of tests with <sup>58</sup>Ni, <sup>28</sup>Si and <sup>12</sup>C beams. Preliminary evaluations of the data show expected performance (or better) and no significant problems.
- □ Mini-EM (2 active layers with full electronics)
  - 24 CDEs have been manufactured, tested and inserted in the structure.
  - AFEE cards have been installed (GCFE9As at cells w/ crystals, GCFE9s at remaining positions.
  - Ready for delivery to SLAC, will ship after holidays.





### **CAL Near Term Milestones**

Monthly Cost / Schedule / Mission Dec 2003

| Activity ID | WBS           | Activity description                               | Early<br>Start | Early<br>Finish | Current<br>Finish | Comments   |
|-------------|---------------|--|----------------|-----------------|-------------------|--|
| 5C1130      | 4.1.5.9.1     | Hadronic beam test                                 | 10-Nov-03      | _               |                   | Done. EM CAL back at NRL on 12/9   |
| 5C61500030  | 4.1.5.6.1.5   | Aluminum Parts Manufacture                         | 3-Nov-03       | 6-Feb-04        |                   | Final comments received from IPO,<br>released on 12/12/03. Baseplate<br>delivery will delay the start of FMA<br>PEM assy |
| 5C61300590  | 4.1.5.6.1.3.2 | AV: Flight Mech Dwgs                               |                | 8-Dec-03        |                   |  |
| 5C62300000  | 4.1.5.6.2.3.1 | IN: Receive FMA Mechanical<br>Struct               |                | 9-Feb-04        |                   |  |
| 5C76000224  | 4.1.5.7.6.1   | Package ASIC Lot T36T                              | 30-Oct-03      | 17-Dec-03       |                   | In process at ASAT. Delivery is  |
| 5C76000228  | 4.1.5.7.6.1   | IA: GCFE9A, GCRC5 for<br>Screen/Qual               |                | 17-Dec-03       |                   |  |
| 5C76000460  | 4.1.5.7.6.1   | 100% functional test<br>GCFE/GCRC                  | 17-Dec-04      | 23-Dec-04       |                   | Need to complete test vector implementation.   |
| 5C76000480  | 4.1.5.7.6.1   | 10% RC Post Burn In Func<br>test<br>(-30C,25C,85C) | 15-Jan-04      | 29-Jan-04       |                   | Need to assemble Variable Temp<br>board and housing. Rent thermal<br>control hood.                                       |
| 5C53100070  | 4.1.5.5.3.1.3 | Receive 1st 600 diodes                             |                | 26-Nov-03       |                   | Done. 1200 Diodes in hand.   |
| 5C57000050  | 4.1.5.5.7     | Fab PDA Lot 1 (600)                                | 2-Dec-04       | 7-Jan-04        |                   | First 150 PDAs are complete.   |
| 5C58200140  | 4.1.5.5.8.2   | Lot 1 - Bond, Clean, Form<br>Wraps                 | 15-Dec-03      | 5-Jan-04        |                   | Starting 12/10   |
| 5C77300120  | 4.1.5.7.7.3   | ND: (5) EM2 TEM/PS for<br>AFEE board ass'y & test  |                | 15-Jan-04       |                   |  |
| 5C77300130  | 4.1.5.7.7.3   | ND: (5) CAL Test Stations for<br>AFEE ass'y & test |                | 15-Jan-04       |                   |  |
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Monthly Cost / Schedule / Mission Dec 2003

#### **DPD Wire Bond failures at Hamamatsu**

#### □ Corrective actions have been implemented

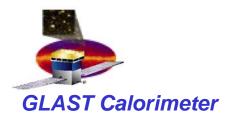
- CAL QA (Nick Virmani) recently completed source inspection visit at Hamamatsu in Japan – No significant problems identified.
- Production is proceeding at a pace to deliver all 4800 diodes to NRL by the end of Jan '04.
- NRL has received ~1200 diodes.
- Flight lot qualification samples have been delivered to GSFC for qualification testing.





- EMI/EMC performance CAL has implemented modifications to mechanical structure to improve EMI/EMC results.
  - Resulting performance will not be known until FMA testing.
  - Outstanding issues:
    - EMI shielding around AFEE-TEM cable
    - Reasonable subsystem EMI/EMC specs and test configurations are still needed.
- □ LAT environmental instrumentation
  - CAL has made no provisions for mounting or routing instrumentation / cabling used in LAT testing.





### Plans for December

Monthly Cost / Schedule / Mission Dec 2003

- □ Ship mini-EM to SLAC.
- Post ship functional test of EM CAL. Change remaining 2 AFEE cards to GCFE9A ASICs.
- □ Build ~72 CDEs. First 12 will be qualification units.
- □ Fab FMA carbon composite structure.
- Receive flight lot (T36T) ASICs and begin functional testing and qualification program.
- □ Assemble and test prototype flight AFEE boards.
- □ Begin manufacture of aluminum parts.
- Complete documentation on ASICs and remaining analyses on AFEE boards.





- Manufacturing delay in base plate could make this the pacing item for completion of FMA. Currently base plate will likely prevent the early start of FMA PEM assembly.
- Readiness and ability to execute the ASIC screening and qualification program as scheduled could also delay delivery of FMA. This is currently the critical path.
- □ Inability to sustain the flight module assembly and test schedule.

